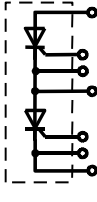
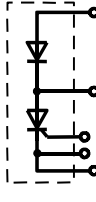
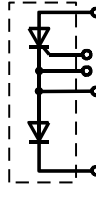


Thyristor/Diode Modules M##220

Absolute Maximum Ratings

V_{RRM} V_{DRM} [V]	 MCC	 MCD	 MDC
2800	220-28io3	220-28io3	220-28io3

	VOLTAGE RATINGS	MAXIMUM LIMITS	UNITS
V_{DRM}	Repetitive peak off-state voltage ¹⁾	2800	V
V_{DSM}	Non-repetitive peak off-state voltage ¹⁾	2900	V
V_{RRM}	Repetitive peak reverse voltage ¹⁾	2800	V
V_{RSM}	Non-repetitive peak reverse voltage ¹⁾	2900	V

	OTHER RATINGS	MAXIMUM LIMITS	UNITS
$I_{T(AV)M}$	Maximum average on-state current, $T_C = 85^\circ\text{C}$ ²⁾	235	A
$I_{T(AV)M}$	Maximum average on-state current, $T_C = 100^\circ\text{C}$ ²⁾	165	A
$I_{T(RMS)M}$	Nominal RMS on-state current, $T_C = 55^\circ\text{C}$ ²⁾	543	A
$I_{T(d.c.)}$	D.C. on-state current, $T_C = 55^\circ\text{C}$	455	A
I_{TSM}	Peak non-repetitive surge $t_p = 10$ ms, $V_{RM} = 60\%V_{RRM}$ ³⁾	5.00	kA
I_{TSM2}	Peak non-repetitive surge $t_p = 10$ ms, $V_{RM} \leq 10$ V ³⁾	5.50	kA
I^2t	I^2t capacity for fusing $t_p = 10$ ms, $V_{RM} = 60\%V_{RRM}$ ³⁾	125	kA ² s
I^2t	I^2t capacity for fusing $t_p = 10$ ms, $V_{RM} \leq 10$ V ³⁾	150	kA ² s
$(di/dt)_{cr}$	Critical rate of rise of on-state current (repetitive) ⁴⁾	100	A/ μ s
$(di/dt)_{cr}$	Critical rate of rise of on-state current (non-repetitive) ⁴⁾	200	A/ μ s
V_{RGM}	Peak reverse gate voltage	5	V
P_{GM}	Peak forward gate power	3	W
V_{ISOL}	Isolation Voltage ⁵⁾	3000	V
$T_{vj\ op}$	Operating temperature range	-40 to +125	$^\circ\text{C}$
T_{stg}	Storage temperature range	-40 to +125	$^\circ\text{C}$

Notes:

- De-rating factor of 0.13% per $^\circ\text{C}$ is applicable for T_{vj} below 25°C .
- Single phase; 50 Hz, 180° half-sinewave.
- Half-sinewave, 125°C T_{vj} initial.
- $V_D = 67\% V_{DRM}$, $I_{FG} = 2$ A, $di_g/dt = 1$ A/ μ s, $T_C = 125^\circ\text{C}$.
- AC RMS voltage, 50 Hz, 1min test

Characteristics

	PARAMETER	MIN.	TYP.	MAX.	TEST CONDITIONS ¹⁾	UNITS
V_{TM}	Maximum peak on-state voltage	-	-	2.00	$I_{TM} = 785 \text{ A}$, $T_{VJ} = 25^\circ\text{C}$	V
V_{TO}	Threshold voltage	-	-	0.90		V
r_T	Slope resistance	-	-	1.10		m Ω
$(dv/dt)_{cr}$	Critical rate of rise of off-state voltage	-	-	1000	$V_D = 80\% V_{DRM}$, linear ramp, Gate o/c	V/ μs
I_{DRM}	Peak off-state current	-	-	50	Rated V_{DRM}	mA
I_{RRM}	Peak reverse current	-	-	50	Rated V_{RRM}	mA
V_{GT}	Gate trigger voltage	-	2.0	-	$T_{VJ} = 25^\circ\text{C}$, $V_D = 12 \text{ V}$, $I_T = 3 \text{ A}$	V
I_{GT}	Gate trigger current	-	150	-		mA
V_{GD}	Gate non-trigger voltage	-	0.25	-	67% V_{DRM}	V
I_L	Latching current	-	-	700	$V_D = 12 \text{ V}$, $T_{VJ} = 25^\circ\text{C}$	mA
I_H	Holding current	-	-	300	$V_D = 12 \text{ V}$, $T_{VJ} = 25^\circ\text{C}$	mA
t_{gd}	Gate controlled turn-on delay time	-	-	3.00	$I_{FG} = 2 \text{ A}$, $t_r = 50 \mu\text{s}$, $V_D = 40\% V_{DRM}$, $I_{TM} = I_{TAV}$, $di/dt = 1 \text{ A}/\mu\text{s}$, $T_{VJ} = 25^\circ\text{C}$	μs
t_q	Turn-off time	-	-	200	$I_{TM} = 235 \text{ A}$, $t_p = 1 \text{ ms}$, $di/dt = 10 \text{ A}/\mu\text{s}$, $V_R = 100 \text{ V}$, $V_{DR} = 67\% V_{DRM}$, $dv_{DR}/dt = 50 \text{ V}/\mu\text{s}$	μs
R_{thJC}	Thermal resistance, junction to case	-	0.1100	-	Single Arm	K/W
		-	0.0550	-	Whole Module	K/W
R_{thCH}	Thermal resistance, case to heatsink	-	0.040	-	Single Arm	K/W
		-	0.020	-	Whole Module	K/W
F_1	Mounting force (to heatsink)	-	6.00	-	²⁾	Nm
F_2	Mounting force (to terminals)	-	9.00	-		Nm
W_t	Weight	-	800	-		g

Notes:

- 1) Unless otherwise indicated $T_{VJ}=125^\circ\text{C}$.
- 2) Screws must be lubricated.

Notes on Ratings and Characteristics

1.0 Voltage Grade Table

Voltage Grade	V_{DRM} V_{RRM} V	V_{DSM} V_{RSM} V	V_D V_R DC V
28	2800	2900	1650

2.0 Extension of Voltage Grades

This report is applicable to other voltage grades when supply has been agreed by Sales/Production.

3.0 De-rating Factor

A blocking voltage de-rating factor of 0.13%/°C is applicable to this device for T_{vj} below 25°C.

4.0 Repetitive dv/dt

Standard dv/dt is 1000V/μs.

5.0 Snubber Components

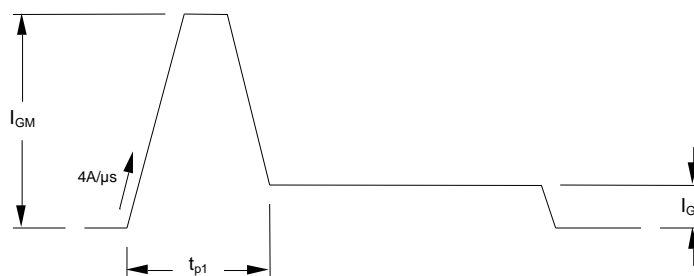
When selecting snubber components, care must be taken not to use excessively large values of snubber capacitor or excessively small values of snubber resistor. Such excessive component values may lead to device damage due to the large resultant values of snubber discharge current. If required, please consult the factory for assistance.

6.0 Rate of rise of on-state current

The maximum un-primed rate of rise of on-state current must not exceed 400A/μs at any time during turn-on on a non-repetitive basis. For repetitive performance, the on-state rate of rise of current must not exceed 200A/μs at any time during turn-on. Note that these values of rate of rise of current apply to the total device current including that from any local snubber network.

7.0 Gate Drive

The nominal requirement for a typical gate drive is illustrated below. An open circuit voltage of at least 30V is assumed. This gate drive must be applied when using the full di/dt capability of the device.



The magnitude of I_{GM} should be between five and ten times I_{GT} , which is shown on page 2. Its duration (t_{p1}) should be 20μs or sufficient to allow the anode current to reach ten times I_L , whichever is greater. Otherwise, an increase in pulse current could be needed to supply the necessary charge to trigger. The 'back-porch' current I_G should remain flowing for the same duration as the anode current and have a magnitude in the order of 1.5 times I_{GT} .

8.0 Computer Modelling Parameters

8.1 Thyristor Dissipation Calculations

$$I_{AV} = \frac{-V_{T0} + \sqrt{V_{T0}^2 + 4 \cdot ff^2 \cdot r_T \cdot W_{AV}}}{2 \cdot ff^2 \cdot r_T} \quad \text{and:} \quad W_{AV} = \frac{\Delta T}{R_{th}}$$

$$\Delta T = T_{j\max} - T_C$$

Where $V_{T0} = 0.9 \text{ V}$, $r_T = 1.10 \text{ m}\Omega$.

R_{th} = Supplementary thermal impedance, see table below and

ff = Form factor, see table below.

Supplementary Thermal Impedance							
Conduction Angle	30°	60°	90°	120°	180°	270°	d.c.
Square wave	3.46	2.45	2	1.73	1.41	1.15	1
Sine wave	3.98	2.78	2.22	1.88	1.57		

Form Factors							
Conduction Angle	30°	60°	90°	120°	180°	270°	d.c.
Square wave	3.464	2.449	2	1.732	1.414	1.149	1
Sine wave	3.98	2.778	2.22	1.879	1.57		

8.2 D.C. Thermal Impedance Calculation

$$r_t = \sum_{p=1}^{p=n} r_p \cdot \left(1 - e^{-\frac{t}{\tau_p}} \right)$$

Where $p = 1$ to n and:

- n = number of terms in the series
- t = Duration of heating pulse in seconds
- r_t = Thermal resistance at time t
- r_p = Amplitude of p_{th} term
- τ_p = Time Constant of r_{th} term

The coefficients for this device are shown in the table below:

D.C.						
Term	1	2	3	4	5	6
r_p	0.1293	0.01314	0.02771	-0.05535	0.0528	0.002749
τ_p	2.823	1.393	0.3322	0.0611	0.05731	0.002713

Outline Drawing & Ordering Information

